

Title (en)  
REWORKABLE THERMOSETTING RESIN COMPOSITIONS

Title (de)  
WIEDERVERARBEITBARE WÄRMEHÄRTBARE HARZZUSAMMENSETZUNGEN

Title (fr)  
COMPOSITIONS DE RESINE THERMODURCISSABLES REMANIABLES

Publication  
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Application  
**EP 00916567 A 20000322**

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Abstract (en)  
[origin: WO0056799A1] This invention relates to thermosetting resin compositions useful for mounting onto a circuit board semiconductor devices, such as chip size or chip scale packages ("CSPs"), ball grid arrays ("BGAs"), and the like, each of which having a semiconductor chip, such as large scale integration ("LSI"), on a carrier substrate. The compositions of this invention are reworkable when subjected to appropriate conditions.

IPC 1-7  
**C08G 59/24**; **H01L 21/56**

IPC 8 full level  
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